Commissioner for Patents: Please record the attached original document(s) or copy(ies).

1. Name of conveying party(ies): Shunpei Yamazaki
   Additional name(s) attached? ☐ Yes ☑ No
   Execution Date: July 21, 2001

2. Name and address of receiving party(ies):
   Semiconductor Energy Laboratory Co., Ltd.
   398 Hase Atsugi-shi
   Kanagawa-ken 243-0036
   JAPAN
   Additional names(addresses) attached? ☐ Yes ☑ No

3. Nature of conveyance:
   ☑ Assignment
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   ☐ Security Agreement
   ☐ Change of Name
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4. Application number(s) or patent number(s):
   If this document is being filed with a new application, the execution date of the application is: July 21, 2001
   B. Patent No.(s): 
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5. Name/address of party to whom correspondence concerning document should be mailed:
   JOHN F. HAYDEN
   Fish & Richardson P.C.
   601 Thirteenth Street, NW
   Washington, DC 20005

6. Total number of applications/patents involved: 1

7. Total fee (37 CFR §3.41): $40
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John F. Hayden
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Signature
July 31, 2001
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PATENT
REEL: 012038 FRAME: 0061
ASSIGNMENT

For valuable consideration, I, Shunpei YAMAZAKI of Setagaya, Tokyo, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan

and its successors and assigns (collectively hereinafter called “the Assignee”), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREFOR filed ________________, and assigned U.S. Serial Number ________________, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors’ certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature: 

Name: Shunpei YAMAZAKI

Date: 07/21/2001